TPG 20013

Integrated Back-End System with Tri-Temp Test Function for Axial Leaded Components



The TPG 200t3 is a fully automatic integrated back-end processing system for axial leaded components. It is the ideal solution when it comes to test, laser mark, sort and tape components such as Hall sensors and transistors in TO packages at high speed and with unprecedented precision. Components can be tested at low temperature, ambient temperature and high temperature. Up to 4 components can be tested simultaneously at each test station. The modular **TPG 200t3** design make the back-end processing system of your choice.

Back-End Technology

With the Geringer TPG 200t3, customer requirements for accuracy and high speed in back-end processing of electronics component can be achieved better than ever.

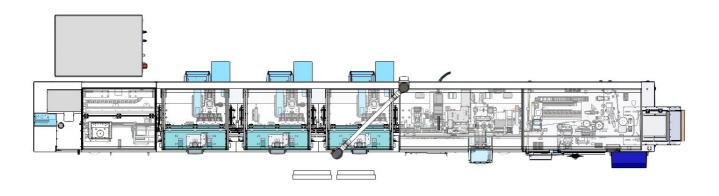
- High throughput
- · Automatic strip feeding from magazine
- Tri-Temp testing
- Laser marking
- · Vision inspection
- Lead forming
- Sorting
- Taping



Innovative production equipment for the semiconductor industry

TPG 200t3

Integrated Back-End System for Axial Leaded Components



Technical Data			
Application	axial leaded components (SOT-195, TO-92, boxed capacitors, film capacitors, crystal oscillators, etc.)		
Component input	lead frames from slot magazine handling system with automatic change over		
Process stations	punching out of tiebars and dambars, lead trimming low tempearture test at -45 °C (Kelvin contacts) ambient tempearture test at +25 °C (Kelvin contacts) high tempearture test at +170 °C (Kelvin contacts) deflashing laser marking vision inspection (surface, mark and lead) component singulation sorting (2 bins standard) lead forming (optionally) taping (ammopack)		
Capacity	depending on test time (e.g. 7,200uph @ 300ms test time)		
Taping specification	Component pitch Taping height	P0 = \pm 0.05mm H = \pm 0.25mm H1 = \pm 0.25mm H2 = \pm 0.25mm	H H H H H H H H H H H H H H H H H H H
	Carrier tape	W = ± 0.5mm	
	Adhesive tape	W0 = 6.0mm	
	Reel sizes	adhesive tape Ø 250mm carrier tape Ø 600mm component reel Ø 360mm max.	P2 F D0 3 x F
	Ammopack size	max. 340mm x 340mm x 55mm	P3 26 Lochabsfände
Dimensions, weight (approx.)	960mm x 7,200mm x 2,040mm (width x length x height) excluding testers and chiller (700mm x 1,000mm x 1,300mm), 3,500 kg		

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